

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all previous versions and listing of claims in the application.

Listing of Claims

Claims 1-15: Cancelled

16. (Withdrawn – Previously Presented) A method for producing a multilayer copper clad laminate by using the electrodeposited copper foil with carrier foil on which a resin layer for forming insulating layer is formed according to claim 18 comprising:

a) drilling a double sided copper clad laminate to be an inner layer board to have holes to be through-holes and/or via-holes, followed by treatment for removing residues if required;

b) plating a thin copper layer inside a wall of the holes made in step a) to provide an inter layer connection;

c) coating the double sided copper clad laminate made in step b) with a plating resist film and then exposing and developing the resist pattern to leave the resist film on the portion where no wiring is formed;

d) electrolytic copper plating on a portion without plating resist film of the double sided copper clad laminate made in step c) to form inner layer wiring pattern and then removing the plating resist film followed by etching of the copper layer on the copper clad laminate to finish inner layer wiring board;

e) laminating the electrodeposited copper foil with carrier foil on which resin layer for forming insulating layer is formed on one side or both sides of the inner layer wiring board made in step d) through hot press, followed by releasing of the carrier foil to get multilayer copper clad laminate which has 3 or more conductive layers.

17. (Withdrawn – Previously Presented) A method for producing a multilayer wiring board by etching the an outer layer copper foil on the multilayer copper clad laminate according to claim 16, comprising:

a) drilling a multilayer copper clad laminate to have holes to be blind via-holes, followed by a treatment for removing residues if required;

b) plating inside walls of the holes made in step 1 with a thin copper layer to finish blind via-holes to provide an inter layer connection;

c) coating multilayer copper clad laminate after finishing plating of thin copper layer made in step b) with a plating resist film and then exposing and developing the resist pattern to leave the plating resist film on the portion where no wiring is formed;

d) electrolytic copper plating on a portion of the multilayer copper clad laminate without the plating resist film to form outer layer wiring pattern and then removing the plating resist film followed by etching of the copper layer on the multilayer copper clad laminate to finish multilayer wiring board.

18. (Currently Amended) An electrodeposited copper foil with carrier foil ~~on which a resin layer for forming an insulating layer is formed~~, comprising:

a carrier foil;

a bonding interface layer formed on top of the carrier foil;

an electrodeposited copper foil layer formed on top of the bonding interface layer having a surface roughness (Rzjis) on both sides of less than 2 μm ;

a rust proofing layer comprising a nickel-zinc alloy formed on top of the electrodeposited copper foil layer, the nickel-zinc alloy having 60 to 80 wt% of Ni and 20 to 40wt% of Zn; and

[[a]] an insulating resin layer formed on top of the rust proofing layer,

wherein the insulating resin layer comprises:

- a) 20 to 80 parts by weight of an epoxy resin including a curing agent;
- b) 20 to 80 parts by weight of a solvent soluble aromatic polyamide resin

polymer; and

- c) optionally a curing accelerator.

19. (Currently Amended) The electrodeposited copper foil with carrier foil ~~on which a resin layer for forming an insulating layer is formed~~ according to claim 18, wherein the aromatic polyamide resin polymer is obtained by a chemical reaction between an aromatic polyamide resin and a rubbery resin.

20. (Currently Amended) The electrodeposited copper foil with carrier foil ~~on which a resin layer for forming an insulating layer is formed~~ according to claim 18, wherein the insulating resin layer comprises a filler composed of a dielectric material.

21. (Currently Amended) The electrodeposited copper foil with carrier foil ~~on which a resin layer for forming an insulating layer is formed~~ according to claim 18, wherein the insulating resin layer comprises a skeletal material.

22. (Currently Amended) The electrodeposited copper foil with carrier foil ~~on which a resin layer for forming an insulating layer is formed~~ according to claim 18, wherein the rustproofing layer additionally comprises a chromate layer.

23. (Canceled)

24. (Currently Amended) The electrodeposited copper foil with carrier foil ~~on which a resin layer for forming an insulating layer is formed~~ according to claim 18, comprising a silane coupling agent layer between the electrodeposited copper foil layer and the insulating resin layer.

25. (Currently Amended) The electrodeposited copper foil with carrier foil ~~on which a resin layer for forming an insulating layer is formed~~ according to claim 24, wherein the silane coupling agent layer is formed by using an amino-functional silane coupling agent or a mercapto-functional silane coupling agent.

26. (Currently Amended) The electrodeposited copper foil with carrier foil ~~on which a resin layer for forming an insulating layer is formed~~ according to claim 18, wherein a thickness of the electrodeposited copper foil layer is 0.5 μm to 12 μm .

27. (Currently Amended) A copper clad laminate comprising ~~obtained by using the~~ electrodeposited copper foil with carrier foil ~~on which a resin layer for forming an insulating layer is formed~~ according to claim 18.

28. (Currently Amended) A printed wiring board comprising ~~obtained by using the~~
electrodeposited copper foil with carrier foil ~~on which a resin layer for forming an insulating~~
~~layer is formed~~ according to claim 18.